

Form PTO-1449
(Substitute)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEAttorney Docket Number
TEGL-01092US1Serial/Patent Number
09/888,365**INFORMATION DISCLOSURE STATEMENT
BY APPLICANT**

(Use several sheets if necessary)

Applicant/Patent Owner
Stephen P. DeOrnellas, et al.Filing/Issue Date
June 22, 2001

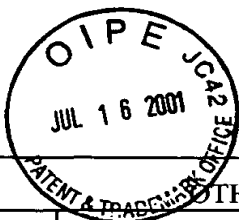
Group Art Unit

U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
PRM	3,514,391	5/26/70	Hablanian et al.	204	298	
	4,033,287	7/5/77	Alexander, Jr., et al.	118	49.1	
	4,208,241	6/17/80	Harshbarger et al.	156	643	
	4,457,359	7/3/84	Holden	165	80	
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	4,512,391	4/23/85	Harra	165	48	
	4,535,834	8/20/85	Turner	165	80	
	4,542,298	9/17/85	Holden	250	443	
	4,680,061	7/14/87	Lamont, Jr.	148	1.5	
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	5,708,557	1/13/98	Feigenbaum et al.	361	234	
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	5,800,619	9/1/98	Holland et al.	118	723	
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Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes No
PRM	JP 07130712 A	5/19/95	Japan			X



OTHER DOCUMENTS (Include Author, Title, Date, Pertinent pages, etc.)	
Ream	Ohno et al., <i>Reactive Ion Etching of Cooper Films in SiCl₄ and N₂ Mixture</i> , Japanese Journal of Applied Physics, Vol.28, No.6, June 1978, pp.11070-1072
	Krogh et al., <i>Spectroscopic Dianostics of Temperature-Controlled Trench Etching of Silicon</i> , Plasma Chemistry Plasma Processes, 10(2), 1990, pp.231-233, 239.
	PCT Notification of Transmittal of the International Search Report or the Declaration for PCT/US98/23297, Int'l Filing Date 03 November 1998, mailed 28 February 2000.
	Alan R. Reinberg, <i>Plasma Etch Equipment Technology, M. Triodes</i> , Perkin-Elmer Corporation, Norwalk, Connecticut, ©1989 by Academic Press, Inc., ISBN 0-12-469370-p; pp. 350-351
↓	Plasma Etching Technology, 10-11 February, 1997, Burlingame, California, Continuing Education in Engineering, University Extension, U. of California, Berkeley, Plasma Etching Technology An Overview , D.L. Flamm, 1992-1996, title 95011501v2, D.L. Flamm 1995, src5012608, 3 pgs
Examiner	Date Considered
Allegandro	03/07/02
<p>*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p> <p>*1 = Copy not submitted because it was submitted in prior application SN / , filed , 19 .</p> <p>*2 = Copy not submitted because it was submitted in prior application SN / , filed , 19 .</p>	

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				Filing/Issue Date Herewith		Group Art Unit Unknown	
U.S. PATENTS							
Examiner Initial		Patent Number	Issue Date	Inventor	Class	Subclass	Filing Date
DDM	1.	5,556,501	09/17/96	Collins et al.	156	345	04/01/93
	2.	5,628,869	05/13/97	Mallon	438	694	05/09/94
	3.	5,800,618	09/01/98	Niori et al.	118	723	06/30/94
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	5.	5,876,504	03/02/99	Fuji et al.	118	723	09/17/97
	6.	5,904,487	05/18/99	Conboy et al.	438	14	10/08/96
✓	7.	6,071,573	06/06/00	Koemtzopoulos et al.	427	578	12/30/97

Examiner <i>Deleandis</i>		Date Considered <i>03/07/02</i>
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